# Server & Storage I/O Connector



## **DDR4 Connector**



#### **OVERVIEW**

Luxshare-TECH's vertical DDR4 DIMM sockets provide 288 contacts on 0.85mm pitch. The DDR4 connector interface could be mated with the DDR4 memory modules that conform to JEDEC MO-309. The DDR4 family support Through Hole and SMT, two solder types. Various pin tail lengths for PCB thickness, compatible to different customer requirements.

Luxshare-TECH DDR4 connectors could support multi-form of DDR4 modules including UDIMM, RDIMM and LRDIMM. Based on excellent performance and diverse options, Luxshare DDR4 product family are widely adopted in PCs, servers, workstations, storage, and embedded applications in communications and industrial equipment.

#### **FEATURES & BENEFITS**

- Through Hole and SMT options avaliable, support diverse hardware design requirement
- Various pin tail lengths for different PCB thickness
- Lower insertion force, easier for module insertion and enough retention force for better reliability
- Narrow housing solutions, Saves board space and benefits air-flow

#### **PRODUCT APPLICATIONS**

Data center & Networking Equipment Servers/Storage Devices High Performance Computing (HPC) Switches/Routers

#### **INDUSTRY STANDARDS**

TH: JEDEC SO-016B SMT: JEDEC SO-017A



### **DDR4** Connector

### **TECHNICAL INFORMATION**

#### MATERIAL

Terminal: Copper Alloy Contact Area Finish: Gold over Nickel Solder Area Finish: Tin over Nickel Board lock: Stainless steel, plated tin over nickel Housing: High temperature thermoplastic(UL 94V-0) Latch: High temperature thermoplastic(UL 94V-0)

#### **ELECTRICAL PERFORMANCE**

Voltage: 30V AC(RMS)/DC Current: 0.75A MAX per contact Differential Impedance: 50±50hms

#### **ENVIRONMENTAL**

Operating temperature : -55°C TO +85°C Storage temperature : +15°C TO +35°C Relative humidity: 20% to 80% Atmospheric pressure: 650mm to 800mm of Hg (86 ~106Kpa)

#### **Partial PN Table**

#### **MECHANICAL PERFORMANCE**

Rated Durability Cycles: 25 Mating Force: 106.8N MAX Unmating Force: 14gf MIN/Per pin pair Retention force- Terminal: 300gf/pin MIN Retention force- Board lock: 13.3N /pin MIN Insertion force - Connector to board: 7.65kgf MAX Preheat: +150° to +180°C / 60~120 seconds Reflow: +230° to +260°C / 30~60 seconds

#### PACKAGING

Tray

#### **SPECIFICATION**

ES-11-00-0003

Product Numbers	Product Description
PDRBB9-5300-003-0H	DDR4+288pin+SMT+30u'' Au+MT+S-L,Tray+HF
PDRBB9-3300-000-0H	DDR4+288pin+TH+30u'' Au+Boardlock+S-L
PDRBB9-3301-000-0H	DDR4+288pin+TH 25 °C+30u Au+with boardlock
PDRBB9-3302-000-0H	DDR4 TH 288Pin 30u'' Au with Boardlock